Unit: mm

TB67S112PGTOSHIBA Photocoupler Photorelay

TLP192A

Telecommunications
Measurement and Control Equipment
Data Acquisition System
Measurement Equipment

The Toshiba TLP192A consists of an infrared emitting diode optically coupled to a photo-MOSFET in a 6-pin SOP package.

Because of the low offset voltage at turn-on, this photorelay is suitable for analog signal switching, eg. micro signal scan circuit of data acquisition system, subscriber circuit of digital exchange.

This photorelay has higher output current rating than phototransistortype photocoupler; hence, it is suitable for use as On/Off control for high current.

• 6-pin SOP (2.54SOP6): Height = 2.1 mm, pitch = 2.54 mm

• Normally open (1-form-A) device

• Peak off-state voltage: 60 V (min)

• Trigger LED current: 3 mA (max)

• On-state current: 400 mA (max)

• On-state resistance: 2 Ω (max)

• Isolation voltage: 1500 Vrms (min)

• UL-recognized: UL 1577, File No.E67349

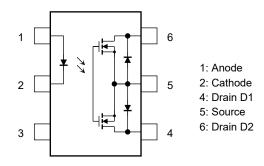
cUL-recognized: CSA Component Acceptance Service No.5A

File No.E67349

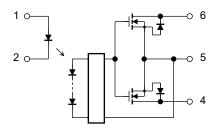
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Weight: 0.13 g (typ.)

Pin Configuration (top view)



Schematic



Start of commercial production 2002-03



Absolute Maximum Ratings (Ta = 25°C)

	(Characteristics	Symbol	Rating	Unit	
	Forward curre	ent	I _F	50	mA	
	Forward curre	ent derating (Ta ≥ 25 °C)	ΔI _F /°C	-0.5	mA/°C	
	Peak forward (100 μs pulse		I _{FP}	1	А	
LED	Reverse volta	ge	V _R	5	V	
	Diode power	dissipation	P _D	50	mW	
	Diode power	dissipation derating (Ta >25 °C)	ΔP _D /°C	-0.5	mW/°C	
	Junction temp	perature	Tj	125	°C	
	Off-state outp	ut terminal voltage	V _{OFF}	60	V	
	On-state current	A connection		400		
		B connection	I _{ON}	400	mA	
		C connection		800		
	Forward current derating (Ta ≥ 25 °C)	A connection		-4.0	mA/°C	
Detector		B connection	ΔI _{ON} /°C	-4.0		
		C connection		-8.0		
	Output power	dissipation	Po	256	mW	
	Output power	dissipation derating (Ta ≥ 25 °C)	ΔP _O / °C	-2.56	mW / °C	
	Junction temp	perature	Tj	125	°C	
Storage temperature			T _{stg}	-55 to 125	°C	
Operating temperature			T _{opr}	-40 to 85	°C	
Lead soldering temperature (10 s)			T _{sol}	260	°C	
Isolation voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1)			BVs	1500	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: LED pins are shorted together. Detector pins are also shorted together.

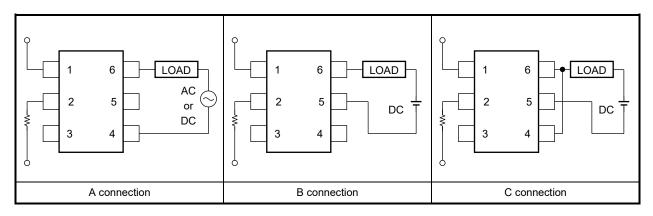
Recommended Operating Conditions

Characteristics	Symbol	Min	Тур.	Max	Unit
Supply voltage	VDD	_	_	48	٧
Forward current	lF	5	7.5	25	mA
On-state current	Ion	_	_	400	mA
Operating temperature	Topr	-20	_	65	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.



Circuit Connections





Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
	Forward voltage	VF	I _F = 10 mA	1.0	1.15	1.3	V
LED	Reverse voltage	I _R	V _R = 5 V	_	_	10	μА
	Capacitance between terminals	CT	V _F = 0 V, f = 1 MHz	_	30	_	pF
Detector	Off-state current	loff	Voff = 60 V	_	_	1	μА
	Capacitance between terminals	Coff	V = 0 V, f = 1 MHz	_	130	_	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Trigger LED current		lfT	I _{ON} = 400 mA	_	1.6	3	mA
Return LED current		IFC	IOFF = 100 μA	0.1	_	_	mA
	A connection	-	ION = 400 mA, IF= 5 mA	_	1	2	
On-state resistance	B connection		I _{ON} = 400 mA, I _F = 5 mA	_	0.5	1	Ω
	C connection		I _{ON} = 800 mA, I _F = 5 mA	_	0.25		

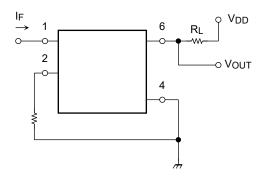
Isolation Characteristics (Ta = 25°C)

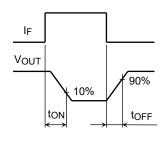
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Capacitance input to output	Cs	V _S = 0 V, f = 1 MHz	_	0.8	_	pF
Isolation resistance	Rs	V _S = 500 V, R.H. ≤ 60 %	5 × 10 ¹⁰	10 ¹⁴	_	Ω
Isolation voltage	BVS	AC, 60 s	1500	_	_	Vrms

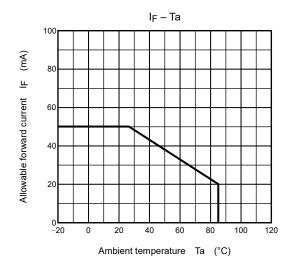
Switching Characteristics (Ta = 25°C)

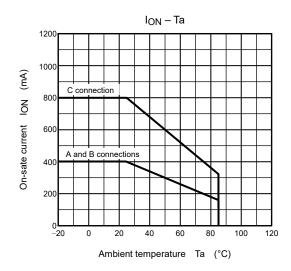
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Turn-on time	ton	$R_L = 200 \Omega$ (Note 2)	_	0.8	2	mo
Turn-off time	toff	$V_{DD} = 20 \text{ V}, I_F = 5 \text{ mA}$	_	0.1	0.5	ms

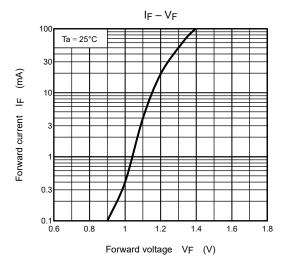
Note 2: Switching time test circuit

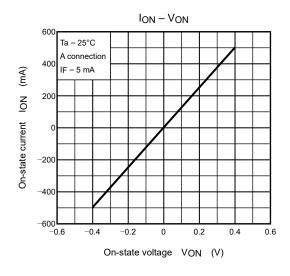


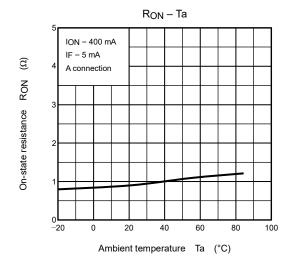


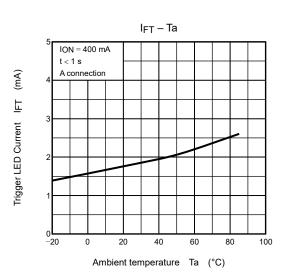




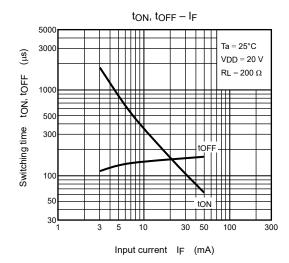


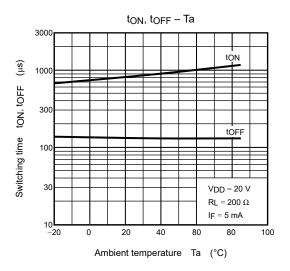


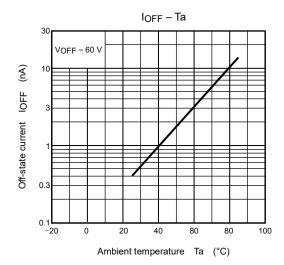




NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.







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